

High Efficiency Regulator Controller

FEATURES

- Complete Control for a High Current, Low Dropout, Linear Regulator
- Fixed 5V or Adjustable Output Voltage
- Accurate 2.5A Current Limiting with Foldback
- Internal Current Sense Resistor
- Remote Sense for Improved Load Regulation
- External Shutdown
- Under-Voltage Lockout and Reverse Voltage Protection
- Thermal Shutdown Protection
- 8 Pin Mini-Dip Package (Surface Mount also Available)

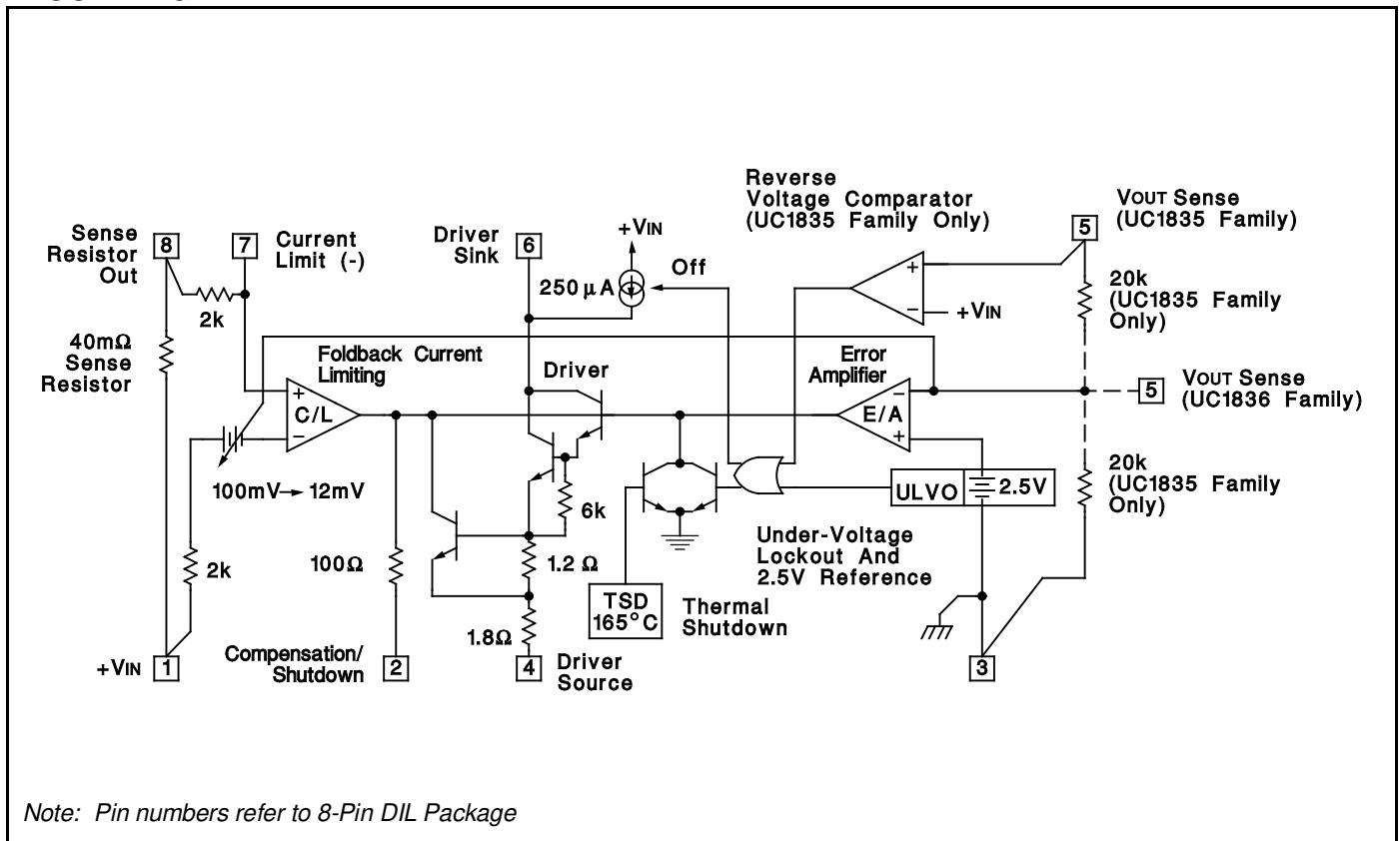
DESCRIPTION

The UC1835/6 families of linear controllers are optimized for the design of low cost, low dropout, linear regulators. Using an external pass element, dropout voltages of less than 0.5V are readily obtained. These devices contain a high gain error amplifier, a 250mA output driver, and a precision reference. In addition, current sense with foldback provides for a 2.5A peak output current dropping to less than 0.5A at short circuit.

These devices are available in fixed, 5V, (UC1835), or adjustable, (UC1836), versions. In the fixed 5 volt version, the only external parts required are an external pass element, an output capacitor, and a compensation capacitor. On the adjustable version the output voltage can be set anywhere from 2.5V to 35V with two external resistors.

Additional features of these devices include under-voltage lockout for predictable start-up, thermal shutdown and short circuit current limiting to protect the driver device. On the fixed voltage version, a reverse voltage comparator minimizes reverse load current in the event of a negative input to output differential.

BLOCK DIAGRAM



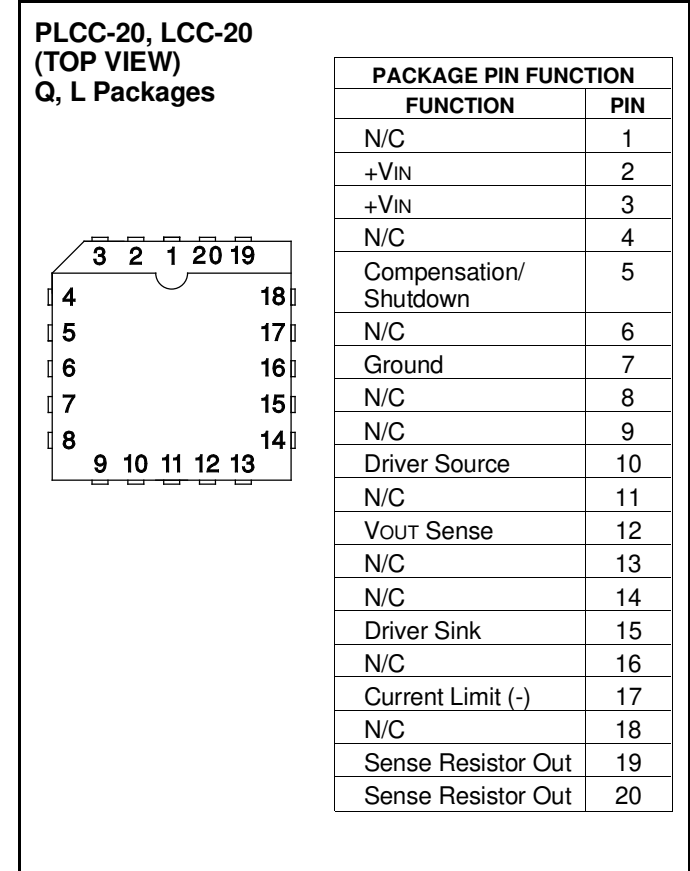
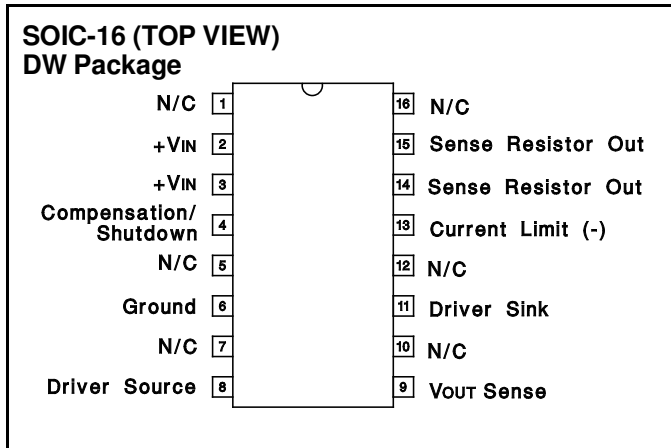
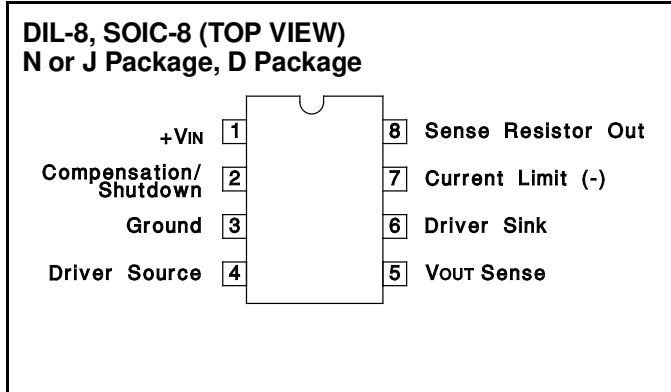
ABSOLUTE MAXIMUM RATINGS (Note 1)

Input Supply Voltage (+VIN) -1.0V to +40V
 Driver Output Current (Sink or Source) 600mA
 Driver Source to Sink Voltage +40V
 Maximum Current Through Sense Resistor. 4A
 VOUT Sense Input Voltage -3V to +40V
 Power Dissipation at TA = 25°C (Note 2) 1000mW
 Power Dissipation at Tc = 25°C (Note 2) 2000mW

Operating Junction Temperature -55°C to +150°C
 Storage Temperature -65°C to +150°C
 Lead Temperature (Soldering, 10 Seconds) 300°C

*Note 1: Voltages are referenced to ground, (Pin 3). Currents are positive into, negative out of, the specified terminals.
 Consult Packaging Section of Databook for thermal considerations and limitations of packages.*

CONNECTION DIAGRAMS



ELECTRICAL CHARACTERISTICS: Unless otherwise stated, specifications hold for TA = 0°C to +70°C for the UC3835/6, -25°C to +85°C for the UC2835/6, and -55°C to +125°C for the UC1835/6, +VIN = 6V, Driver Source= 0V, Driver Sink = 5V, TA = TJ.

PARAMETER	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Input Supply					
Supply Current	+VIN = 6V		2.75	4.0	mA
	+VIN = 40V		3.75	6.0	mA
UVLO Threshold	+VIN Low to High, VOUT Sense = 0V	3.9	4.4	4.9	V
Threshold Hysteresis			0.1	0.35	V
Reverse Current	+VIN = -1.0V, Driver Sink Open		6.0	20	mA
Regulating Voltage and Error Amplifier (UC1835 Family Only)					
Regulating Level at VOUT Sense (VREG)	Driver Current = 10mA, TJ = 25°C	4.94	5.0	5.06	V
	Over Temperature	4.9		5.1	V
Line Regulation	+VIN = 5.2V + 35V		15	40	mV
Load Regulation	Driver Current = 0 to 250mA		6.0	25	mV
Bias Current at VOUT Sense	VOUT Sense = 5.0V	75	125	210	µA
Error Amp Transconductance	±100µA at Compensation/Shutdown Pin	0.8	1.3	2.0	mS
Maximum Compensation Output Current	Sink or Source, Driver Source Open	90	200	260	µA

ELECTRICAL CHARACTERISTICS: Unless otherwise stated, specifications hold for $T_A = 0^\circ\text{C}$ to $+70^\circ\text{C}$ for the UC3835/6, -25°C to $+85^\circ\text{C}$ for the UC2835/6, and -55°C to $+125^\circ\text{C}$ for the UC1835/6, $+V_{IN} = 6\text{V}$, Driver Source = 0V , Driver Sink = 5V , $T_A = T_J$.

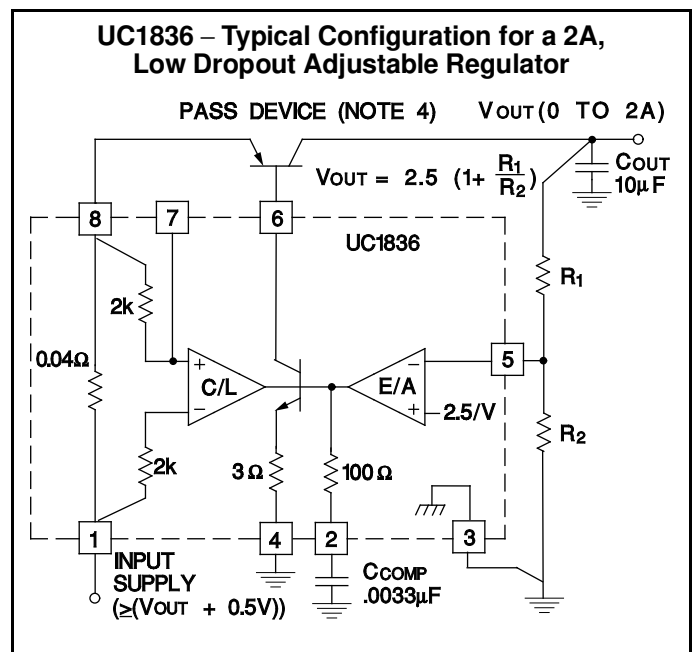
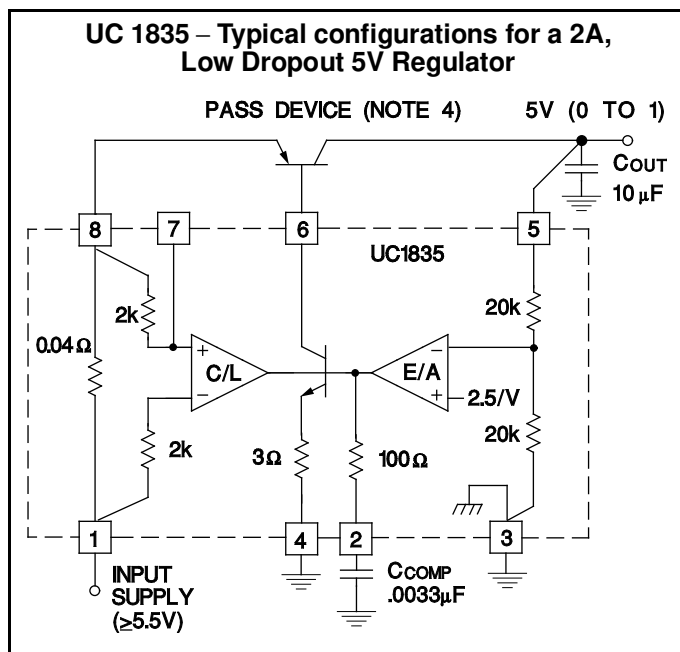
PARAMETER	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Regulating Voltage and Error Amplifier (UC1836 Family Only)					
Regulating Level at V_{OUT} Sense (V_{REG})	Driver Current = 10mA , $T_J = 25^\circ\text{C}$	2.47	2.5	2.53	V
	Over Temperature	2.45		2.55	V
Line Regulation	$+V_{IN} = 5.2\text{V}$ to 35V		6.0	20	mV
Load Regulation	Driver Current = 0 to 250mA		3.0	15	mV
Bias Current at V_{OUT} Sense	V_{OUT} Sense = -2.5V	-1.0	-0.2		μA
Error Amp Transconductance	$\pm 100\mu\text{A}$ at Compensation/Shutdown Pin	0.8	1.3	2.0	mS
Maximum Compensation Output Current	Sink or Source, Driver Source Open	90	200	260	μA
Driver					
Maximum Current		250	500		mA
Saturation Voltage	Driver Current = 250mA , Driver Sink		2.0	2.8	V
Pull-Up Current at Driver Sink	Compensation/Shutdown = 0.45V	140	250	300	μA
Driver Sink Leakage	In UVLO			10	μA
	In Reverse Voltage (UC1835 Family Only)			10	μA
Thermal Shutdown			165		$^\circ\text{C}$
Foldback Current Limit					
Current Limit Levels at Sense Resistor Out	V_{OUT} Sense = $(0.99) V_{REG}$	2.2	2.5	2.8	A
	V_{OUT} Sense = $(0.5) V_{REG}$	1.3	1.5	1.7	A
	V_{OUT} Sense = 0V	0.25	0.4	0.55	A
Current Limit Amp Transconductance	$\pm 100\mu\text{A}$ at Compensation/Shutdown, V_{OUT} Sense = $(0.9) V_{REG}$	12	24	42	mS
Limiting Voltage at Current Limit (-) (Note 2)	V_{OUT} Sense = $(0.9) V_{REG}$ Volts Below $+V_{IN}$, $T_J = 25^\circ\text{C}$	80	100	140	mV
Sense Resistor Value (Note 3)	V_{OUT} Sense = $(0.9) V_{REG}$, $I_{OUT} = I_A$, $T_J = 25^\circ\text{C}$		40		$\text{m}\Omega$

Note 2: This voltage has a positive temperature coefficient of approximately $3500\text{ppm}/^\circ\text{C}$.

Note 3: This resistance has a positive temperature coefficient of approximately $3500\text{ppm}/^\circ\text{C}$.

The total resistance from Pin 1 to Pin 8 will include an additional 60 to $100\text{m}\Omega$ of package resistance.

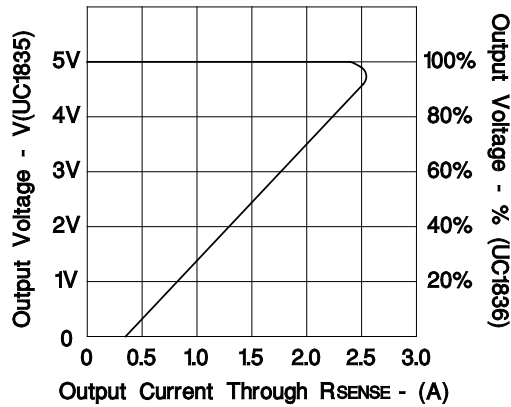
APPLICATION AND OPERATION INFORMATION



Note 4: Suggested Pass devices are TIP 32B. (Dropout Voltage $\leq 0.75\text{V}$) or, D45H, (Dropout Voltage $\leq 0.5\text{V}$), or equivalents.

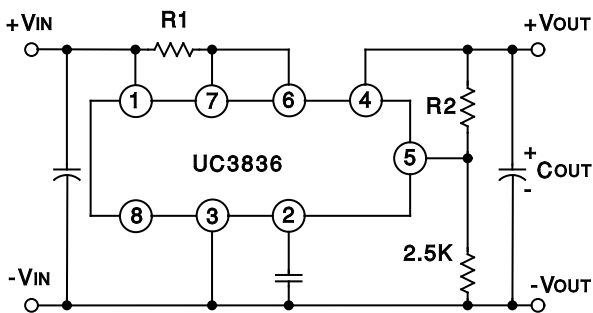
APPLICATION AND OPERATION INFORMATION (cont.)

UC1835/6 Foldback Current Limiting



UC3835/36 TYPICAL APPLICATIONS

Low Current Application
 using the UC3836 internal drive transistor

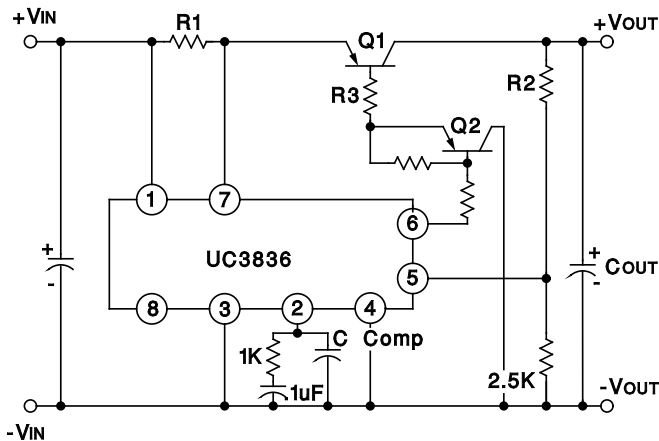


Typical Output Current vs VIN and VOUT
 of the UC3836 internal drive transistor
 for PDISS = 0.5W (approx.)

		VIN						
		Volts	5	9	12	15	18	24
VOUT	2	150	60	40	30	20	12	
	5		105	55	35	25	15	
	9			130	60	35	20	
	12				120	55	25	
	15					110	30	
		Current in mA						

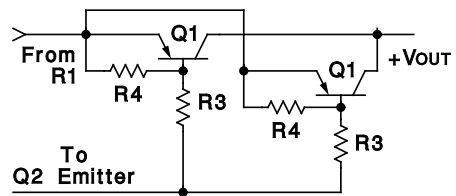
High Current Application

using drive transistor Q2 to increase Q1 base drive
 and reduce UC3836 power dissipation



Parallel Pass Transistors

can be added for high current or
 high power dissipation applications



EQUATIONS:

$$R1 = 0.100 V/I_{OUT} (MAX)$$

$$R2 = (V_{OUT} - 2.5V/1mA)$$

$$R3 = ((V_{IN} - V_{BE} - V_{SAT}) * BETA(min)) / I_{OUT} (max)$$

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-9065002PA	ACTIVE	CDIP	JG	8	1	TBD	A42 SNPB	N / A for Pkg Type
UC1835J	OBSOLETE	CDIP	JG	8		TBD	Call TI	Call TI
UC1835J883B	OBSOLETE	CDIP	JG	8		TBD	Call TI	Call TI
UC1835L883B	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI
UC1836J	ACTIVE	CDIP	JG	8	1	TBD	A42 SNPB	N / A for Pkg Type
UC1836J883B	ACTIVE	CDIP	JG	8	1	TBD	A42 SNPB	N / A for Pkg Type
UC1836L	OBSOLETE	TO/SOT	L	20		TBD	Call TI	Call TI
UC1836L883B	OBSOLETE	TO/SOT	L	20		TBD	Call TI	Call TI
UC2835D	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UC2835DG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UC2835J	OBSOLETE	CDIP	JG	8		TBD	Call TI	Call TI
UC2835N	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
UC2835NG4	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
UC2836D	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UC2836DG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UC2836DTR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UC2836DTRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UC2836DW	OBSOLETE	SOIC	DW	16		TBD	Call TI	Call TI
UC2836DWTR	ACTIVE	SOIC	DW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UC2836DWTRG4	ACTIVE	SOIC	DW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UC2836N	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
UC2836NG4	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
UC3835N	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
UC3835NG4	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
UC3836D	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UC3836DG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UC3836DTR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UC3836DTRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UC3836N	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
UC3836NG4	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSELETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

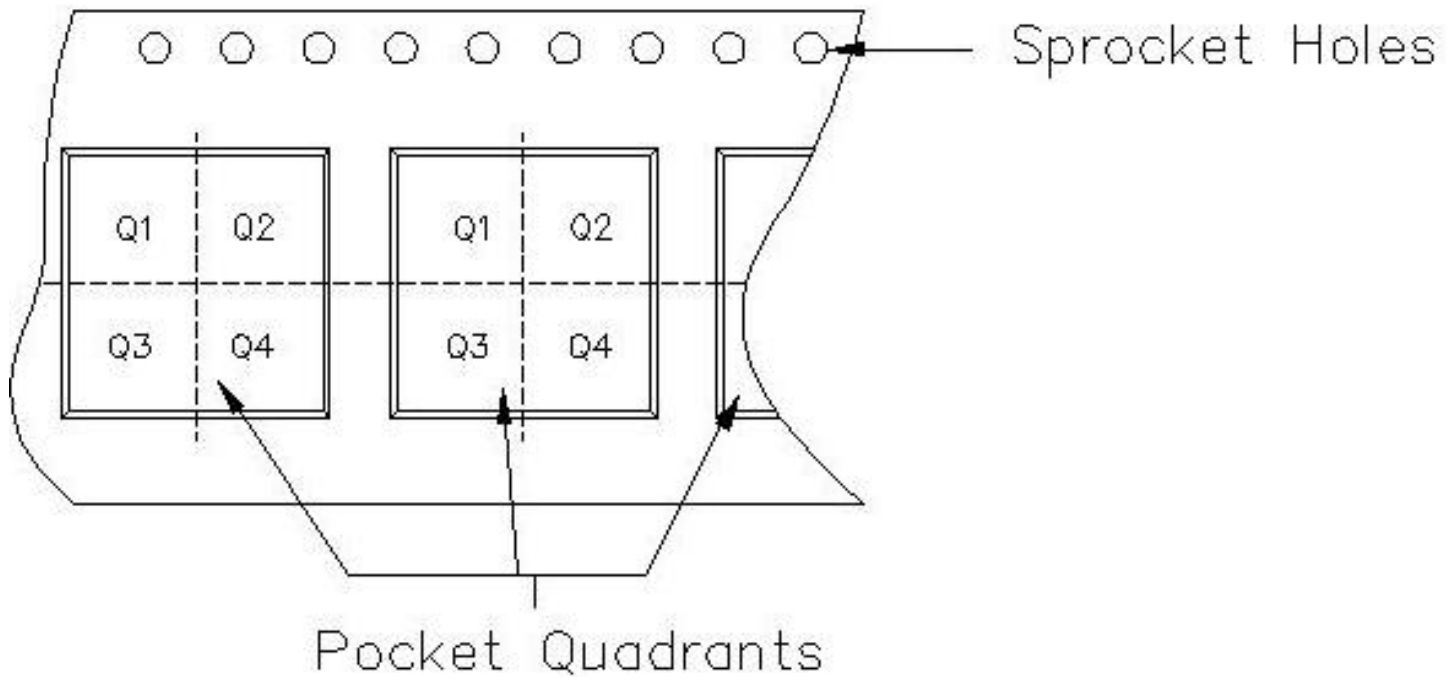
Important Information and Disclaimer:The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.



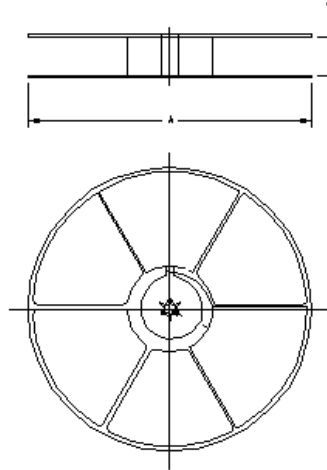
Carrier tape design is defined largely by the component length, width, and thickness.

A_o = Dimension designed to accommodate the component width.
B_o = Dimension designed to accommodate the component length.
K_o = Dimension designed to accommodate the component thickness.
W = Overall width of the carrier tape.
P = Pitch between successive cavity centers.



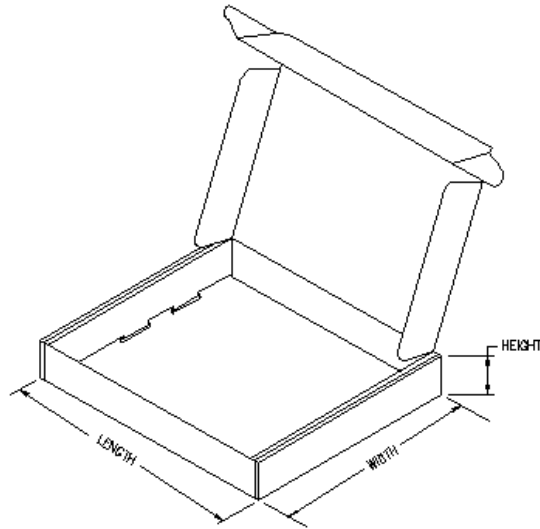
TAPE AND REEL INFORMATION

Device	Package	Pins	Site	Reel Diameter (mm)	Reel Width (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
UC2836DTR	D	8	CRS	0	0	6.4	5.2	2.1	8	12	Q1
UC3836DTR	D	8	CRS	0	0	6.4	5.2	2.1	8	12	Q1



TAPE AND REEL BOX INFORMATION

Device	Package	Pins	Site	Length (mm)	Width (mm)	Height (mm)
UC2836DTR	D	8	CRS	342.9	336.6	28.58
UC3836DTR	D	8	CRS	342.9	336.6	28.58



IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products

Amplifiers	amplifier.ti.com
Data Converters	dataconverter.ti.com
DSP	dsp.ti.com
Interface	interface.ti.com
Logic	logic.ti.com
Power Mgmt	power.ti.com
Microcontrollers	microcontroller.ti.com
Low Power Wireless	www.ti.com/lpw

Applications

Audio	www.ti.com/audio
Automotive	www.ti.com/automotive
Broadband	www.ti.com/broadband
Digital Control	www.ti.com/digitalcontrol
Military	www.ti.com/military
Optical Networking	www.ti.com/opticalnetwork
Security	www.ti.com/security
Telephony	www.ti.com/telephony
Video & Imaging	www.ti.com/video
Wireless	www.ti.com/wireless

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2007, Texas Instruments Incorporated